In the Claims

1. (currently amended) An apparatus for performing operations on a surface of an electronic substrate, the apparatus comprising:

a frame;

a dispenser, coupled to the frame, to dispense a material onto the electronic substrate;

a stencil translatable on a gantry system, the stencil having at least one aperture to receive the material as the material is dispensed on the substrate by the dispenser;

a controller that controls dispensing of the material on the substrate; and

a fixed wiper to remove material from the stencil as the stencil is translated away from the electronic substrate by the gantry system and over the fixed wiper.

2-3. (canceled)

4. (currently amended) The apparatus of claim ~~3~~ 1, further comprising an inspecting probe coupled to a second gantry system for inspecting a surface on the electronic substrate.

5. (original) The apparatus of claim 4, wherein the inspecting probe is moveable to a position over the electronic substrate.

6. (original) The apparatus of claim 5, wherein the stencil translates over the fixed wiper substantially simultaneously with the inspecting of the electronic substrate.

7. (currently amended) The apparatus of claim 1, wherein the fixed wiper is positioned below the position of the stencil.

8. (currently amended) The apparatus of claim 1, wherein the stencil translates from a first front position, to a second back position, and returns to the first front position upon removal of the material by the fixed wiper.

9. (original) The apparatus of claim 1, wherein the stencil translates away from the electronic substrate by moving orthogonally to the position of the electronic substrate.

10. (currently amended) The apparatus of claim 1, wherein the stencil translates in a first direction away from the electronic substrate and translates in a second direction toward the fixed wiper.

11. (original) A method for performing a printing operation on a surface of a substrate, the method comprising:

transporting the substrate into a position for printing a material onto the substrate;

aligning the substrate and a stencil, the stencil having at least one aperture to receive the material as the material is deposited onto the substrate;

depositing the material through the stencil and onto the substrate; and

translating the stencil from a position over the surface of the substrate, over a fixed wiper positioned to remove a residual material from the surface of the stencil as the stencil is translated.

12. (original) The method of claim 11 further comprising inspecting the substrate using a video probe inspection system.

13. (original) The method of claim 12 wherein the steps of inspecting and translating occur substantially simultaneously.

14. (original) The method of claim 11 further comprising transporting a second substrate to a printing position while translating the stencil over the fixed wiper.

15. (previously presented) A method for simultaneously inspecting an electronic substrate and cleaning a stencil in a stencil printer, the method comprising:

positioning the stencil above the electronic substrate;

depositing a material on the electronic substrate;

separating the stencil and the electronic substrate;

translating the stencil to a position removed from the area over the circuit board;

inserting an inspecting system in a space between the stencil and the electronic substrate; and

inspecting the electronic substrate while translating the stencil over a fixed wiper for cleaning.